

LIDROTEC Raises \$13.5 Million to Revolutionize Chip Singulation

25 June 2025 – **LIDROTEC**, a deep tech start-up pioneering next-generation laser systems for low-damage, high-precision chip cutting, has announced the successful closing of a \$13.5 million Series A-2 financing round. The round was co-led by Lam Capital, the corporate venture arm of semiconductor fabrication equipment and services company Lam Research Corporation, and Goose Capital. New investors ZEISS Ventures and NRW.BANK joined the round and bring strong technical, operational and scale-up expertise. Existing investors including Goose Capital, Gründerfonds Ruhr and others contributed well above their pro rata.

LIDROTEC's proprietary laser systems combine high-precision cutting with fluid-based cooling and cleaning, reducing material damage, heat affected zone width, and particle defects in grooving and dicing processes. This results in dramatically lower breakage rates and higher yields, particularly for difficult-to-dice hard materials and thin semiconductors.

This latest investment will enable LIDROTEC to accelerate product development and commercialization, grow its team, and deliver its novel liquid-mediated laser dicing solutions to both the compound semiconductor and leading-edge semiconductor markets.

"This funding is a major validation of our technology, team, and vision," said Alexander Igelmann, Co-Founder and CEO of LIDROTEC. "The support from both leading financial and strategic partners gives us the firepower to scale globally and help address the pressing inefficiencies in chip production."

"LIDROTEC's novel approach to chip singulation has the potential to deliver significant yield improvements to companies in the power device, photonics, and semiconductor sectors. We've been impressed with the team and their technology since their strong showing at Lam Capital's 2024 Venture Competition and are looking forward to seeing their capabilities commercialized," said **Kevin Chen**, managing director of **Lam Capital** and corporate development at **Lam Research**. LIDROTEC also recently appointed Ben Haskell, investment director at Lam Capital, to its board of directors.

"We've backed LIDROTEC since their first round and have only grown more confident in their potential to become a core enabler in semiconductor manufacturing," said **Ashok Rao**, Board Member at **Goose Capital**. "This team is solving a deeply technical problem with global relevance, and we're proud to double down as they enter their next stage of growth."

“We see LIDROTEC as a key player in the next wave of semiconductor equipment innovation,” said **Mike Gaenssler**, Investment Manager at **ZEISS Ventures**. “Their unique approach directly addresses critical challenges in wafer processing, and we’re excited to support their expansion from both an industrial and strategic perspective.”

“LIDROTEC has a proven track record of deep-tech innovation and is tackling highly relevant growth areas such as Advanced Packaging & High Bandwidth Memory,” said **Thorsten Reuter**, Head of Digital & Technology Ventures at **NRW.BANK** as well as Managing Director at **Gründerfonds Ruhr**. “We seek out technologies that are highly scalable and globally relevant, and LIDROTEC fits that profile perfectly. We are delighted to join this exceptional syndicate with NRW.BANK and to increase our commitment with Gründerfonds Ruhr.”

With the semiconductor sector increasing focus on throughput and yield, LIDROTEC’s solution comes at a crucial time for the industry.